

SEARCH REQUEST FORM**Scientific and Technical Information Center**

Requester's Full Name: POTHIER Examiner #: 74010 Date: 5-2-02
 Art Unit: 3764 Phone Number 308-0993 Serial Number: 09475 69625 792
 Mail Box and Bldg/Room Location: 3D 09 Results Format Preferred (circle): PAPER DISK E-MAIL

If more than one search is submitted, please prioritize searches in order of need.

Please provide a detailed statement of the search topic, and describe as specifically as possible the subject matter to be searched. Include the elected species or structures, keywords, synonyms, acronyms, and registry numbers, and combine with the concept or utility of the invention. Define any terms that may have a special meaning. Give examples or relevant citations, authors, etc, if known. Please attach a copy of the cover sheet, pertinent claims, and abstract.

Title of Invention: Medical Instrument With a Non-Contact Readable D.C. Carrier
 Inventors (please provide full names): Hartmut Bache

Earliest Priority Filing Date: 7-26-99

For Sequence Searches Only Please include all pertinent information (parent, child, divisional, or issued patent numbers) along with the appropriate serial number.

An ^{medical} instrument used ~~as~~ with an endoscope. It includes a non-contact wireless carrier (transponder with an antenna) that sends environmental ~~- includes circuit & data memory unit~~ parameters, such as temperature, pressure, humidity, radiation, & shock or impact loads. This information is carried to a remote location ~~to gather data from the carrier~~.

The carrier is embedded into the instrument and encased in a medium. The medium could be silicone, epoxy resin, duroplastic material, cement, or ceramic. This medium floats the carrier to protect against physical & mechanical shock or loads.

The material of the medium and the instrument itself differ in elasticity modulus and heat conductivity in order to guard against shock and loads. ~~A medium carrier~~

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STAFF USE ONLY

Type of Search	Vendors and cost where applicable
NA Sequence (#)	STN _____
AA Sequence (#)	Dialog _____
Structure (#)	Questel/Orbit _____
Bibliographic	Dr.Link _____
Litigation	Lexis/Nexis _____
Fulltext	Sequence Systems _____
Patent Family	WWW/Internet _____
Other	Other (specify) _____

14/7/1 (Item 1 from file: 2)

DIALOG(R)File 2:INSPEC

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5803195 INSPEC Abstract Number: B9802-7230-068, C9802-3240N-016

Title: Remotely-queried wireless embedded microsensors in composites

Author(s): Krantz, D.G.; Belk, J.H.

Journal: Proceedings of the SPIE - The International Society for Optical Engineering Conference Title: Proc. SPIE - Int. Soc. Opt. Eng. (USA) vol.3044 p.219-26

Publisher: SPIE-Int. Soc. Opt. Eng,

Publication Date: 1997 Country of Publication: USA

CODEN: PSISDG ISSN: 0277-786X

SICI: 0277-786X(1997)3044L.219:RQWE;1-J

Material Identity Number: C574-97181

U.S. Copyright Clearance Center Code: 0277-786X/97/\$10.00

Conference Title: Smart Structures and Materials 1997: Industrial and Commercial Applications of Smart Structures Technologies

Conference Sponsor: SPIE; SEM; ASME

Conference Date: 4-6 March 1997 Conference Location: San Diego, CA, USA

Language: English Document Type: Conference Paper (PA); Journal Paper (JP)

Treatment: Practical (P); Experimental (X)

Abstract: Embedding sensors in structural composites has been a topic of research in recent years. Embedded sensors can be used to monitor and optimize the manufacturing process, to monitor performance during use, and for structural health monitoring in high-performance applications. The US Naval Research Laboratory is funding a multi-disciplinary team to develop micro-machined sensors and an associated remote-querying capability to allow self-contained microsensors to be embedded in a composite structure and queried using methods that do not require physical connections. The sensors are to be left in place for the lifetime of the structure, are powered by the querying apparatus, and require no penetrations through the surface of the structure. Part of this work included studying electromagnetic propagation into graphite- epoxy (conductive) composites. A key part of this research has been the development of embeddable antennae that can operate within a conductive composite matrix with the efficiency required to both absorb power for the circuitry and to transmit and receive data. This paper describes the integrated approach taken to realize the goal of an interrogatable strain rosette that is embedded 0.25" into a graphite composite plate. Aspects of the sensors, the transponder, and the antenna are also covered. (5 Refs)

Subfile: B C

Copyright 1998, IEE

14/7/2 (Item 2 from file: 2)

DIALOG(R)File 2:INSPEC

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5715334 INSPEC Abstract Number: B9711-7230-036

Title: An overview of the remotely-queried embedded microsensors program

Author(s): Krantz, D.G.; Belk, J.H.

Conference Title: Symposium on Antenna Technology and Applied Electromagnetics 1996 Conference Proceedings p.811-14

Publisher: Univ. Manitoba, Winnipeg, Man., Canada

Publication Date: 1996 Country of Publication: Canada 838 pp.

Material Identity Number: XX96-02326

Conference Title: Proceedings of Symposium on Antenna Technology and Applied Electromagnetics

Conference Date: 6-9 Aug. 1996 Conference Location: Montreal, Que., Canada

Language: English Document Type: Conference Paper (PA)

Treatment: Applications (A); General, Review (G)

Abstract: Embedding sensors in structural composites has been a topic

of research in recent years. **Embedded** sensors can be used to monitor and optimize the manufacturing process, and for structural health monitoring in high-performance applications. To date, optical fiber sensors have been the principal sensing technique for these applications. There are well-known problems with optical fiber sensors, including manufacturing costs and fragility in ingress and egress from the structure, and the interdependence of strain and temperature measurements. The USA Naval Research Laboratory is funding a multi-disciplinary team to develop micro-machined sensors and an associated remote-querying capability to allow self-contained microsensors to be **embedded** in a composite structure and queried using methods that do not require physical connections. The sensors are to be left in place for the lifetime of the structure, are powered by the querying apparatus, and require no penetrations through the surface of the structure. Part of this work includes studying electromagnetic propagation into graphite- **epoxy** (conductive) composites. A key part of this research has been the development of **embeddable** antennas that can operate within a conductive composite matrix with the efficiency required to both absorb power for the circuitry and to transmit and receive data. This paper describes the integrated approach taken to realize the goal of an interrogatable strain rosette that is **embedded** 0.25 inch into a graphite composite plate. Aspects of the sensors, the **transponder**, and the antenna are also covered. (0 Refs)

Subfile: B

Copyright 1997, IEE

14/7/3 (Item 1 from file: 34)

DIALOG(R)File 34:SciSearch(R) Cited Ref Sci
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04795477 Genuine Article#: UH442 Number of References: 8

Title: EVALUATION OF ELECTRONIC IDENTIFICATION TRANSPONDERS IMPLANTED IN THE RUMEN OF CATTLE

Author(s): HASKER PJS; BASSINGTHWAIGHTE J

Corporate Source: QUEENSLAND DEPT PRIMARY IND,GPO BOX 46/BRISBANE/QLD
4001/AUSTRALIA/; AUSTRALIAN MEAT & LIVESTOCK CORP/BRISBANE/QLD
4001/AUSTRALIA/

Journal: AUSTRALIAN JOURNAL OF EXPERIMENTAL AGRICULTURE, 1996, V36, N1, P 19-22

ISSN: 0816-1089

Language: ENGLISH Document Type: ARTICLE

Abstract: The performance of electronic identification transponders **encased** in **ceramic** capsules inserted into the reticulo-rumen was assessed in 3 groups of cattle: 1059 two-year-old feedlot steers, 11 penned calves and 46 grazing calves. Insertion of capsules presented little difficulty and at slaughter, examination of the reticulorumen showed no visible signs of damage to the reticulo-endothelium due to the capsules. The retention rate of the capsules was 100% in adults when slaughtered 55-107 days after capsules were inserted. All Losses of capsules from calves occurred before calves were 21 weeks of age. Transponders were successfully read both in the live animal and in the body on the slaughter chain. All transponders in the reticulorumen of grazing calves were functioning normally up to 46 weeks after being implanted. At slaughter, capsules were recovered easily with no risk of contaminating meat or by-products. Small steel metallic objects near the capsule appeared not to affect the reading distance of the **transponder**.

14/7/4 (Item 1 from file: 108)

DIALOG(R)File 108:AEROSPACE DATABASE
(c) 2002 AIAA. All rts. reserv.

02364367 A98-42630

An integrated circuit to operate a transponder with embeddable **MEMS** microsensors for structural health monitoring

Neuzil, P.; Serry, F. M.; Krenek, O.; Maclay, G. J.
In: Structural health monitoring - Current status and perspectives;
Proceedings of the International Workshop, Stanford Univ., CA, Sept. 18-20,
1997 (A98-42601 11-31), Lancaster, PA, Technomic Publishing Co., Inc.,
1997, p. 492-501.

1997

CONTRACT NO.: N00014-94-C-2231

LANGUAGE: English

COUNTRY OF ORIGIN: United States COUNTRY OF PUBLICATION: United States

DOCUMENT TYPE: CONFERENCE PAPER

DOCUMENTS AVAILABLE FROM AIAA Technical Library

JOURNAL ANNOUNCEMENT: IAA9811

We present the design and the results of tests performed on a CMOS IC which interfaces with MEMS capacitive sensors and with an antenna coil for **embedding** inside physical structures to monitor local stress and strains.

Using inductive coupling, the IC powers itself from a pilot signal at 130 kHz, which it receives from an interrogating device called the Reader. The IC then makes measurements of the sensor's output and converts the measurement to a binary code, which is then transmitted to the Reader by differential phase-shift-key (DPSK) modulation of a 65-kHz signal across the antenna coil. The IC has roughly 3000 transistors and was fabricated using 2-micron double-poly- silicon , double-metal technology at a commercial foundry. The IC uses a Delta-Sigma A/D converter for the measurement of the capacitance of a sensing capacitor as compared with that of a reference capacitor (Author)

14/7/5 (Item 1 from file: 248)

DIALOG(R)File 248:PIRA

(c) 2002 Pira International. All rts. reserv.

00343730 Pira Acc. Num.: 10231072 Pira Abstract Numbers: 03-93-01526

Title: PLASTIQUE'S EXPLOSIVE POTENTIAL

Authors: Dawson S

Source: Storage Handl. Distrib. vol. 37, no. 1, Jan. 1993, pp 40, 42

ISSN: 0039-1832

Publication Year: 1993

Document Type: Journal Article

Language: English

Pira Subfiles: International Packaging Abstracts (PK)

Journal Announcement: 9304

Abstract: Three new products have been developed by Allibert Handling, part of the Sommer Allibert Group, based in Gloucester and these are reviewed. The first is a reusable delivery pallet for holding dynamic loads up to 500kg as well as 1 tonne static loads. The Packpal is available in eight variations based on 80 x 1200 and 1000 x 1200mm, in ventilated or solid deck versions. They are stable to minus 40 deg C. With a capacity of 78 litres, the Allibert Distribution Box has an integral hinged lid and an innovative water channel and perimeter seal to restrict water ingress up to 80-90%. It may be stacked up to six high. A compact trolley, the Multimover, which may be transported in a car boot, accepts loads up to 300kg and has a tough **epoxy** coated handle. This is available in fold and lock format or detachable. Planned developments include a new wheelie bin. Also, to allow tracking within the manufacturing and storage process, the possibility of **embedding** low cost Texas Instruments' transponders within pallets is being explored. Illustrations are included.
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39th Annual R&D 100 Awards. (Cover Story) (Industry Overview)

R & D, 43, 9, 29
Sept, 2001

... R&D 100 Awards banquet takes place Thursday, October 4, 2001, at Chicago's Museum of Science & Industry.

Winner	Page Number
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3rdTech Inc.	61
Advanced Ceramics Research	57
Advanced Engine Technology Ltd.	68
Advanced Fuel Research	57, 64
Agilent Technologies Inc.	65
Aisan Industry Co.	58
Amcast Industrial Corp.	66

Ameritherm...also have good contrast (~10:1) and a wide viewing angle. The printed plastic transistors and circuits that incorporate them have excellent performance (similar to **silicon**-based circuits) in a format that is suitable for low resolution signs, electronic newspapers, or other high information content displays.

This development required pulling together...other solutions.

www.2dgels.com

Write In 2058

Analytical Instruments

Monolithic Column Material Aids HPLC

Chromolith materials by Merck KGaA, Darmstadt, Germany, are the first **silicon**-based monolithic separation materials for high performance liquid chromatography. Products such as Chromolith Speed ROD RP-18e (50-4.6 mm) and Chromolith Performance RP...mm, and relies on volume production and high reliability. The volume production is automatic hybrid integration for the laser diode coupled by fiber' onto a **silicon** chip-on-carrier with micron accuracy with plastic dual-in-line flat package. The high reliability is based on a **silicone** transparent gel encapsulation technique that maintains high reliability under high temperature and humidity.

The HL1328DJS from Hitachi Ltd., Tokyo, and Nortel Networks, Paignton, UK, is...

...attached directly to a ship. The transponders acoustically talk to each other setting up a calibrated 3-D underwater grid. The diver dons a tracking **transponder** and head-mounted display. Not only can a diver's position be accurately determined and mapped with SeaViz, the system can be used to guide...temperature capabilities of the metallic structural components in the engine hot section. It is generally agreed that upper temperature limits of metals have been reached. **Ceramics** exhibit superior high-temperature strength and durability, but **silicon**-based **ceramics** suffer from rapid surface recession in combustion environments due to reaction with corrosive species.

Two new coatings-- **Silicon**/Mullite/BSAS and **Silicon**/Mullite+BSAS/BSAS EBCs (Environmental Barrier Coatings)--protect **silicon**-based **ceramics** from harsh environmental attacks, most notably water vapor and molten salts. In combustion environments, the new coatings dramatically improve the performance of **silicon**-based **ceramics** and have accumulated 14,000 hrs of operation at ~1250 (degrees) C.

The coatings were developed by a team of researchers from NASA Glenn Research...Martin Aeronautics Company, Fort Worth, Texas; and NASA Langley Research Center, Hampton, Va.

www.mccookmetals.com

Write In 2083

New Process Creates ECOCERAMICS

Environment Conscious **Ceramics** (ECOCERAMICS) are a new class of materials fabricated by pyrolysis of natural wood or wood sawdust or their combinations. The manufacturing process is suitable for producing dense or

porous **ceramics** of non-oxide and oxide systems.

The microstructure, composition, and thermomechanical properties of ECO CERAMICS can be tailored according to component design and application requirements. A number of key material properties such as strength, toughness, and **environmental** and **thermal shock** resistance can be achieved by utilizing variations in microstructural design and composition. ECO CERAMICS maintain their reliability at high temperatures and exhibit mechanical properties and environmental resistance comparable to traditional **ceramics**.

This manufacturing process was developed by researchers at NASA John H. Glenn Research Center at Lewis Field, Cleveland, and M. Singh from Dynacs Engineering Co. Inc., Cleveland.

www.nasa.gov

Write In 2084

Treatment Toughens SiC Fibers

Sylramic-iBN **Silicon**-Carbide (SiC) Fiber is the result of a NASA-developed treatment for commercial Sylramic fiber that significantly improves intrinsic and surface fiber properties and provides **ceramic** composites with the highest available thermostructural properties.

Developed by James DiCarlo and Hee Mann Yun at the NASA Glenn Research Center, Cleveland, and John Brennan...

...conventional coatings in wear resistance, bonding, and machinability of the coated part, according to developer Peter Strutt.

The new coatings, nanostructured versions of alumina-titania **ceramic** composites, obtain their improved mechanical properties from their small grain size, which is on the order of less than 100 nm. Compared to conventional micron...

...of coated parts over a wide range of device and component applications.

www.inframat.com

Write In 2096

Easy to use Mandrel

Aquacore, from Advanced **Ceramics** Research, Tucson, Ariz., is a water soluble, lightweight and environmentally friendly mandrel material designed for use in the manufacture of high-end composites. The product... reduces vapors by simply shrinking as the amount of fuel in the tank is reduced. This Vapor Reduction Fuel Tank System-Bladder Tank has a **resin** membrane that expands and shrinks. The membrane is placed in a metal outer tank to form a double tank system. The inspiration for the project...of steel or magnetic material, cars are naturally magnetized. A magneto-impedance sensor, housed in a duralumin shell and measuring only 25 mm thick is **embedded** in a road. MIDAD was developed by Toyota's Yutaka Nonomura and a team of researchers.

www.tylabs.co.jp

Write In 2043

A Wafer...

...has developed a cost-effective, compliant, and precise test contact system that allows circuits to be tested and packaged while they are still on the **silicon** wafer.

FormFactor's MicroSprings on **Silicon** Technology or MOST bonds thousands of gold-coated springs directly to **silicon** wafers. The resilient spring contacts become the compliant test interfaces, as well as the final package interconnect elements. MOST's partner technology, WOW (Wafer-on...materials. The product is the only viscosity measurement technology that uses millimeter-wave electromagnetic radiation to probe the movement of liquids. It uses a hollow **ceramic** waveguide that can withstand the hot and corrosive environment inside the melter.

The maximum fluid temperature is greater than 1500 (degrees) C, while the maximum...

...frequency spectrum. Films with a thickness of less than 10 nm can be tested on substrates with low ultrasonic attenuation such as single crystals of **silicon**. Apart from coatings, the method can be used to study damage and diffusion layers.

LAWave was developed by Dieter Schneider and Thomas Schwarz at
Fraunhofer...
?

7/7/1 (Item 1 from file: 5)
DIALOG(R)File 5:Biosis Previews(R)
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13557142 BIOSIS NO.: 200200185963

Encasement and transducer shuttle assembly for removable implanted device.

AUTHOR: Wedan Steven R(a); Johnson Rebecca M

AUTHOR ADDRESS: (a)Savage, MN**USA

JOURNAL: Official Gazette of the United States Patent and Trademark Office
Patents 1255 (2):pNo Pagination Feb. 12, 2002

MEDIUM: e-file

ISSN: 0098-1133

DOCUMENT TYPE: Patent

RECORD TYPE: Abstract

LANGUAGE: English

ABSTRACT: An implantable and extractable **sensor** is used for monitoring blood flow and vessel characteristics within a patient. The **sensor** includes a structurally supportive shuttle that has an angularly offset shelf. A transducer is mounted to this shelf and offset at the same angle so as to utilizes the Doppler effect. **Silicone** is injection molded around the assembly to provide a housing having a plurality of cutouts that expose portions of release wires running through the housing. The **sensor** is attached to the vessel by suturing around the exposed portions of the release wires. When the wires are retracted, the **sensor** can be extracted from the patient without having to reopen the **surgical** wound. The shuttle provides a consistent location to mount a transducer and also provides the structural support for the **silicone** housing.

7/7/12 (Item 1 from file: 2)

DIALOG(R)File 2:INSPEC

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02296256 INSPEC Abstract Number: A84085539, B84044708

Title: Inaccurate temperature sensors

Author(s): Ben-Zvi, S.

Author Affiliation: Sci. & Medical Instrumentation Center, State Univ. of New York, Brooklyn, NY, USA

Journal: Journal of Clinical Engineering vol.9, no.1 p.72-3

Publication Date: Jan.-March 1984 Country of Publication: USA

CODEN: JCEND7 ISSN: 0363-8855

Language: English Document Type: Journal Paper (JP)

Treatment: Practical (P)

Abstract: Temperature probes are used to monitor blood temperature during open-heart **surgery**. A fault in a Yellow Springs Instruments Series 416 temperature probe is discussed. The fault was due to the **epoxy resin encasing** the thermistor not having cured properly, allowing etching of the thermistor. Checking of such probes is described. (0 Refs)

Subfile: A B

7/7/13 (Item 1 from file: 8)

DIALOG(R)File 8:Ei Compendex(R)

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05543178 E.I. No: EIP00045146404

Title: Single module, tets and telemetry operated hermetically sealed controller for the Jarvik 2000 heart totally implantable system (J2000-TI)

Author: Jacobs, G.; Valenta, H.; McClure, R.; Doer, V.; Sherman, C.; Pham, Hai; Takeuchi, Esther; Albright, J.; Marlinski, E.; Tamez, D.; Conger, J.; Jarvik, R.

Corporate Source: Transicoil Medical LLC

Conference Title: 46th Annual Conference and Exposition of ASAIO

Conference Location: New York, NY, USA Conference Date:

19000628-19000701

E.I. Conference No.: 56674

Source: ASAIO Journal v 46 n 2 Mar-Apr 2000. p 179

Publication Year: 2000

CODEN: ASATEJ ISSN: 1058-2916

Language: English

Document Type: JA; (Journal Article) Treatment: G; (General Review)

Journal Announcement: 0006W2

Abstract: A single module, TETS and telemetry operated, hermetically sealed controller compatible with the dual coil Jarvik 2000 intraventricular axial flow rotary blood pump has been designed, fabricated, tested in vitro, and implanted in a 74-kg calf at the Texas Heart Institute (ongoing at 65 days). The purpose of this paper is to describe the design philosophy, fabrication techniques relevant to the pacemaker-style packaging concepts and bench testing results leading up to this first in vivo implant. Included within the single module are microprocessor based electronics (with manual and automatic modes) and internal batteries (3 X prismatic C cells, 1.4 AH) provided by Wilson Greatbatch (WG) LTD. The electronics includes main (M) and backup (BU) motor controllers, M and BU TETS power conditioners, an RF telemetry link, battery charging circuitry, and appropriate **sensors**. These are packaged within a hermetically sealed titanium can using WG - Hittman feedthroughs **embedded** in an **epoxy**, pacemaker-style header (MedSource) designed to accept a unipolar ECG lead, two triaxial connectors (M and BU stators), and two biaxial connectors (M and BU TETS). External to the body are a TETS oscillator, primary coil, 4 X D li-ion battery pack and power supply. Pre-operative submerged saline testing demonstrated system efficiencies of 6-8% depending on load and internal temperatures of 47-50 degree C. (Author abstract)

7/7/14 (Item 2 from file: 8)

DIALOG(R) File 8:Ei Compendex(R)

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04341581 E.I. No: EIP96023020923

Title: **Interfacing microsystems and biological systems**

Author: Dario, Paolo; Carrozza, Maria Chiara

Corporate Source: ARTS/Mitech Lab, Pisa, Italy

Conference Title: Proceedings of the 1995 6th International Symposium on Micro Machine and Human Science

Conference Location: Nagoya, Jpn Conference Date: 19951004-19951006

Sponsor: IEEE

E.I. Conference No.: 44284

Source: Proceedings of the International Symposium on Micro Machine and Human Science 1995. IEEE, Piscataway, NJ, USA, 95TH8079. p 57-66

Publication Year: 1995

CODEN: 85RUA6

Language: English

Document Type: CA; (Conference Article) Treatment: A; (Applications); G ; (General Review)

Journal Announcement: 9603W5

Abstract: Micromechatronic systems integrate miniature precision mechanisms, actuators, **sensors** and **embedded** control. Their intrinsic features are electively suitable for application in the medical field, in particular when miniaturization, reliability and intimate interaction with the human body are required. Microsystems can be exploited for acute intervention or for permanent (short and long term) implant in the human body. This paper focuses on microsystems for permanent implant, and discusses their problems and perspectives with reference to some representative fields of application. Such fields include **sensory** substitution (such as microsystems for hearing aids, artificial eyes and artificial touch); internal organs substitution (in particular microsystems for drug delivery and micro bio-artificial organs); and neural prostheses (an example of regeneration-type neural interface is presented where axons regenerate through metalized holes microfabricated in a **silicon** dice). We

conclude that medical applications of microsystems and micromachines may have a tremendous impact on the quality of medical care and become a very attractive industrial market, provided that some key technical problems are addressed and solved. (Author abstract) 36 Refs.

7/7/15 (Item 3 from file: 8)
DIALOG(R)File 8:Ei Compendex(R)
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02082385 E.I. Monthly No: EIM8604-019924
Title: MONOLITHIC FLEXIBLE THERMOMETER ARRAYS FOR USE IN CANCER HYPERTHERMIA.

Author: Barth, Phillip W.; Angell, James B.
Corporate Source: Stanford Univ, Integrated Circuits Lab, Stanford, CA, USA

Conference Title: Proceedings of the Symposium on Biosensors.
Conference Location: Los Angeles, CA, USA Conference Date: 19840915
Sponsor: IEEE Engineering in Medicine & Biology Soc, New York, NY, USA.; NSF, Washington, DC, USA.; Alliance for Engineering in Medicine & Biology, Bethesda, MD, USA.; AICHE, New York, NY, USA.; Assoc for the Advancement of Medical Instrumentation, Arlington, VA, USA.; et al.

E.I. Conference No.: 05719
Source: Publ by IEEE, New York, NY, USA Available from IEEE Service Cent (Cat n 84CH2068-5), Piscataway, NJ, USA p 24-26

Publication Year: 1984

Language: English

Document Type: PA; (Conference Paper)

Journal Announcement: 8604

Abstract: Batch-fabricated thermometer arrays have been developed for temperature profile measurement during hyperthermia treatment of cancer. An array consists of 20 **silicon** islands interconnected by flexible gold leads, both **embedded** in a flexible polyimide layer. Each island contains one p-n diode, which is used as a thermometer. The linear arrays are 1 mm wide by 0.4 mm thick; array lengths of 20 cm, 10 cm, and 3.5 cm have been designed, and fabrication of the 3.5-cm arrays is complete. Two arrays can be simultaneously connected to a portable microcomputer-based system for calibration, data acquisition, temperature profile display, and data logging onto floppy diskettes. The flexible array fabrication technology also lends itself to two-dimensional arrays of **sensors** for robotic and biomedical uses. 3 refs.

?

1/26, TI/1 (Item 1 from file: 350)
DIALOG(R) File 350:Derwent WPIX
(c) 2002 Thomson Derwent. All rts. reserv.
014261879
WPI Acc No: 2002-082577/200211
Beam-forming for downlink channel in CMDA-based, multipath mobile radio telephone system, optimizes directivities and powers in relation to application-specific upper threshold

1/26, TI/2 (Item 2 from file: 350)
DIALOG(R) File 350:Derwent WPIX
(c) 2002 Thomson Derwent. All rts. reserv.
013815682
WPI Acc No: 2001-299894/200131
Method and structure for forming a rake receiver's beams for single user reception for an uplink channel in a mobile radio telephone system uses a linear antenna array with antenna elements in series with a rake receiver and rake fingers.

1/26, TI/3 (Item 3 from file: 350)
DIALOG(R) File 350:Derwent WPIX
(c) 2002 Thomson Derwent. All rts. reserv.
013514510
WPI Acc No: 2000-686456/200067
Determining first moment of frequency spectrum of time signal e.g. for examination of speech signals by adding multiplied signal to parallelly routed signal and integrating

1/26, TI/4 (Item 4 from file: 350)
DIALOG(R) File 350:Derwent WPIX
(c) 2002 Thomson Derwent. All rts. reserv.
013474982
WPI Acc No: 2000-646925/200062
Controlling and dynamically adapting directional characteristics of linear antenna arrays for spatially separating signals by comparing calculated directivity with minimum value for required quality

1/26, TI/5 (Item 5 from file: 350)
DIALOG(R) File 350:Derwent WPIX
(c) 2002 Thomson Derwent. All rts. reserv.
013414905
WPI Acc No: 2000-586843/200055
Producing defined directional characteristics of directional antenna for wireless mobile radio systems

1/26, TI/6 (Item 6 from file: 350)
DIALOG(R) File 350:Derwent WPIX
(c) 2002 Thomson Derwent. All rts. reserv.
012336413
WPI Acc No: 1999-142520/199912
Device for limiting force transmission to surgical instruments - involves at least one wedge surface forming part of an operating component and rising crossways to movement direction of operating component

1/26, TI/7 (Item 7 from file: 350)
DIALOG(R) File 350:Derwent WPIX
(c) 2002 Thomson Derwent. All rts. reserv.

012336412

WPI Acc No: 1999-142519/199912

Surgical grasping and holding pliers - is for handling ball-shaped, used swabs and has shaft with at least two mouth parts at distal end with grips at shaft proximal end

1/26, TI/8 (Item 8 from file: 350)

DIALOG(R) File 350:Derwent WPIX

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011583805

WPI Acc No: 1998-000934/199801

Sewing appliance for minimal invasive surgery on human being or animal - has support with relatively movable guide tube and operating rod linked by lever and has linkage fixed to angle lower end of operating rod

File 350:Derwent WPIX 1963-2001/UD,UM &UP=200230

File 344:CHINESE PATENTS ABS APR 1985-2002/APR

File 347:JAPIO Oct/1976-2001/Dec(Updated 020503)

File 371:French Patents 1961-2002/BOPI 200209

Set Items Description

S1 8 AU='BOCHE H'

1/6/1 (Item 1 from file: 348)

01028313

SURGICAL GRASPING AND HOLDING PLIERS

1/6/2 (Item 2 from file: 348)

01028078

DEVICE FOR LIMITING THE FORCE TRANSMITTED TO SURGICAL INSTRUMENTS

1/6/3 (Item 3 from file: 348)

00906617

SUTURING AID

1/6/4 (Item 1 from file: 349)

00473351 **Image available**

DEVICE FOR LIMITING THE FORCE TRANSMITTED TO SURGICAL INSTRUMENTS

Publication Year: 1999

1/6/5 (Item 2 from file: 349)

00473350 **Image available**

SURGICAL GRASPING AND HOLDING PLIERS

Publication Year: 1999

1/6/6 (Item 3 from file: 349)

00402136 **Image available**

SUTURING AID

Publication Year: 1997

File 348:EUROPEAN PATENTS 1978-2002/May W01

File 349:PCT FULLTEXT 1983-2002/UB=20020509,UT=20020502

Set Items Description

S1 6 AU='BOCHE HARTMUT'

```
### Status: Path 1 of [Dialog Information Services via Modem]

### Status: Initializing TCP/IP using (UseTelnetProto 1 ServiceID dialog.com)
Trying 31060000009999...Open

DIALOG INFORMATION SERVICES
PLEASE LOGON:
***** HHHHHHHH SSSSSSS?
### Status: Signing onto Dialog
*****
ENTER PASSWORD:
***** HHHHHHHH SSSSSSS? *****
Welcome to DIALOG
### Status: Connected
```

Dialog level 02.05.06D

Last logoff: 15may02 13:59:01
Logon file415 15may02 14:34:31
MEDPATBIB is set ON as an alias for 350,344,347,371.

File 415:DIALOG Bluesheets(TM) 2002/May 15
(c) 2002 The Dialog Corporation

Set	Items	Description
---	---	-----
Cost is in DialUnits		
?B155,144,5,6,2,8,99,238,65,77,73,34,434,94,35		
15may02 14:34:48 User262807 Session D3145.1		
\$0.00 0.082 DialUnits File415		
\$0.00 Estimated cost File415		
\$0.05 TELNET		
\$0.05 Estimated cost this search		
\$0.05 Estimated total session cost 0.082 DialUnits		

SYSTEM:OS - DIALOG OneSearch
File 155: MEDLINE(R) 1966-2002/May W1
*File 155: This file has been reloaded. Accession numbers have changed.
File 144: Pascal 1973-2002/May W2
(c) 2002 INIST/CNRS
File 5: Biosis Previews(R) 1969-2002/May W2
(c) 2002 BIOSIS
File 6: NTIS 1964-2002/May W3
(c) 2002 NTIS, Intl Cpyrght All Rights Res
*File 6: See HELP CODES6 for a short list of the Subject Heading Codes
(SC=, SH=) used in NTIS.
File 2: INSPEC 1969-2002/May W2
(c) 2002 Institution of Electrical Engineers
File 8: Ei Compendex(R) 1970-2002/May W2
(c) 2002 Engineering Info. Inc.
File 99: Wilson Appl. Sci & Tech Abs 1983-2002/Apr
(c) 2002 The HW Wilson Co.
File 238: Abs. in New Tech & Eng. 1981-2002/May
(c) 2002 Reed-Elsevier (UK) Ltd.

File 65:Inside Conferences 1993-2002/May W2
 (c) 2002 BLDSC all rts. reserv.
 File 77:Conference Papers Index 1973-2002/Mar
 (c) 2002 Cambridge Sci Abs
 File 73:EMBASE 1974-2002/May W1
 (c) 2002 Elsevier Science B.V.
 *File 73: For information about Explode feature please
 see Help News73.
 File 34:SciSearch(R) Cited Ref Sci 1990-2002/May W2
 (c) 2002 Inst for Sci Info
 File 434:SciSearch(R) Cited Ref Sci 1974-1989/Dec
 (c) 1998 Inst for Sci Info
 File 94:JICST-EPlus 1985-2002/Mar W4
 (c) 2002 Japan Science and Tech Corp (JST)
 *File 94: There is no data missing. UDs have been adjusted to reflect
 the current months data. See Help News94 for details.
 File 35:Dissertation Abs Online 1861-2002/Apr
 (c) 2002 ProQuest Info&Learning

Set	Items	Description
---	-----	
?s wireless		
	S1 72717	WIRELESS
?s noncontact or non() contact		
	15877	NONCONTACT
	6350810	NON
	856653	CONTACT
	15442	NON (W) CONTACT
	S2 28920	NONCONTACT OR NON() CONTACT
?s contactless		
	S3 14174	CONTACTLESS
?s carrier? ?		
	S4 805030	CARRIER? ?
?s transponder? ?		
	S5 9982	TRANSPOUNDER? ?
?s transmitter?(2n) receiver?		
	151035	TRANSMITTER?
	224187	RECEIVER?
	S6 19678	TRANSMITTER? (2N) RECEIVER?
?s silicone		
	S7 87423	SILICONE
?s epoxy()resin		
	157460	EPOXY
	263427	RESIN
	S8 52660	EPOXY()RESIN
?s duroplastic or duraplastic		
	104	DUROPLASTIC
	8	DURAPLASTIC
	S9 112	DUROPLASTIC OR DURAPLASTIC
?s cement		
	S10 151436	CEMENT
?s ceramic? ?		
	S11 509020	CERAMIC? ?
?save temp		
Temp SearchSave "TD214" stored		
?ds		

Set Items Description
S1 72717 WIRELESS
S2 28920 NONCONTACT OR NON() CONTACT
S3 14174 CONTACTLESS
S4 805030 CARRIER? ?
S5 9982 TRANSPONDER? ?
S6 19678 TRANSMITTER?(2N) RECEIVER?
S7 87423 SILICONE
S8 52660 EPOXY() RESIN
S9 112 DUROPLASTIC OR DURAPLASTIC
S10 151436 CEMENT
S11 509020 CERAMIC? ?
?s s1:s3(3n)s4:s6
 114288 S1:S3
 831502 S4:S6
 S12 845 S1:S3(3N)S4:S6
?s s7:s11
 S13 783550 S7:S11
?s s12 and s13
 845 S12
 783550 S13
 S14 8 S12 AND S13
?rd
...completed examining records
 S15 5 RD (unique items)
?t15/6,k/all
>>>KWIC option is not available in file(s): 77

15/6,K/1 (Item 1 from file: 144)
DIALOG(R)File 144:(c) 2002 INIST/CNRS. All rts. reserv.

14776317 PASCAL No.: 00-0455626
Initial investigations on systems for measuring intraocular pressure
Proceedings of Eurosensors XIII, The Hague, The Netherlands, 12-15
September 1999: Micromechanics Section
2000

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... sensor was connected to a microwire. In a second version, the sensor was connected to transponder components for wireless data and energy transmission. Both versions were encapsulated in standard soft intraocular lens material. Pressure...

...after encapsulation. In addition, a small offset was observed due to the influence of the silicone coating. The performances of the sensors have the same precision as widely accepted gold standard...

15/6,K/2 (Item 1 from file: 99)
DIALOG(R)File 99:(c) 2002 The HW Wilson Co. All rts. reserv.

1109699 H.W. WILSON RECORD NUMBER: BAST93041826
Ultrasonic measurements of surface roughness
19930701

...ABSTRACT: in the same way as light, pulsed ultrasound propagating in

water was employed at megahertz carrier frequencies. Noncontact ultrasonic techniques were considered in the following ways: for specific applications such as wet surfaces...

...real-time sensor feedback and process control in the cutting and grinding of metals and ceramics .

15/6,K/3 (Item 1 from file: 94)
DIALOG(R)File 94:(c)2002 Japan Science and Tech Corp(JST). All rts.
reserv.

02552324 JICST ACCESSION NUMBER: 95A0626839 FILE SEGMENT: JICST-E
Liquid crystal display technologies of 1995.From components and materials
to manufacturing processes. Noncontact material carrier technology.
, 1995

Liquid crystal display technologies of 1995.From components and materials
to manufacturing processes. Noncontact material carrier technology.
...BROADER DESCRIPTORS: ceramics

15/6,K/4 (Item 2 from file: 94)
DIALOG(R)File 94:(c)2002 Japan Science and Tech Corp(JST). All rts.
reserv.

02219733 JICST ACCESSION NUMBER: 94A0615185 FILE SEGMENT: JICST-E
Special issue : Production engineering of a liquid crystal display.
Contactless carrier device for a large and ultrathin type liquid
crystal glass substrate., 1994

Special issue : Production engineering of a liquid crystal display.
Contactless carrier device for a large and ultrathin type liquid
crystal glass substrate.
...BROADER DESCRIPTORS: ceramics ;

15/6,K/5 (Item 3 from file: 94)
DIALOG(R)File 94:(c)2002 Japan Science and Tech Corp(JST). All rts.
reserv.

01940676 JICST ACCESSION NUMBER: 94A0128342 FILE SEGMENT: JICST-E
ID System. COB Assembly and The Reliability. A Method Which Establishes
Wire Bonding Condition of C-MOS Bare Chip IC., 1993

ABSTRACT: We have developped a small one, sized .PHI.8*5(mm), as the data
carrier of non - contact ID system. This data carrier is made of COB
assembly of bare chip IC in...

...as soon as possible. C-MOS IC is different from Bi-Polar IC and the
silicone ingredient included in its pattern exerts a serious influence
on assembly stress. As a results...

?t15/7/1,3,4,5

15/7/1 (Item 1 from file: 144)
DIALOG(R)File 144:Pascal
(c) 2002 INIST/CNRS. All rts. reserv.

14776317 PASCAL No.: 00-0455626
Initial investigations on systems for measuring intraocular pressure
Proceedings of Eurosensors XIII, The Hague, The Netherlands, 12-15
September 1999: Micromechanics Section
SCHNAKENBERG U; WALTER P; BOEGEL G V; KRUEGER C; LUEDTKE-HANDJERY H C;
RICHTER H A; SPECHT W; RUOKONEN P; MOKWA W
MIDDELHOEK S, ed
Institute for Materials in Electrical Engineering I, RWTH Aachen,
Sommerfeldstrasse 24, 52074 Aachen, Germany; Department of Ophthalmology,
University of Cologne, Germany; Fraunhofer Institute of Microelectronic
Circuits and Systems, Duisburg, Germany; Institute for Pathology, RWTH
Aachen, Germany
Eurosensors: International Conference on Solid-State Sensors and
Actuators, 13 (The Hague NLD) 1999-09-12
Journal: Sensors and actuators. A, Physical, 2000, 85 (1-3) 287-291
ISSN: 0924-4247 Availability: INIST-19425A; 354000091904070460
No. of Refs.: 13 ref.
Document Type: P (Serial); C (Conference Proceedings) ; A (Analytic)
Country of Publication: Switzerland
Language: English
Basic investigations on an intraocular implant system for continuous
measurements of the intraocular pressure (IOP) are introduced. The system
consists of a pressure sensor connected to transponder components
integrated in the haptic of an artificial soft intraocular lens. External
transponder components will be integrated in a spectacle and a hand-held
unit. The influence of the lens material on the pressure sensor performance
will be discussed in detail. Two pre-version of the concept mentioned will
be introduced. In the first version, a pressure sensor was connected to a
microwire. In a second version, the sensor was connected to transponder
components for wireless data and energy transmission. Both versions were
encapsulated in standard soft intraocular lens material. Pressure
measurements show the same sensitivity before and after encapsulation. In
addition, a small offset was observed due to the influence of the silicone
coating. The performances of the sensors have the same precision as widely
accepted gold standard for the determination of the IOP.

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15/7/3 (Item 1 from file: 94)
DIALOG(R) File 94:JICST-EPlus
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02552324 JICST ACCESSION NUMBER: 95A0626839 FILE SEGMENT: JICST-E
Liquid crystal display technologies of 1995. From components and materials
to manufacturing processes. Noncontact material carrier technology.
HASHIMOTO YOSHIKI (1); KOIKE YOSHIKAZU (2); UEHA SADAYUKI (2)
(1) Kaijo Corp.; (2) Tokyo Inst. of Technol.
Denshi Zairyo(Electronic Parts and Materials), 1995, NO.July,bessatsu,
PAGE.127-130, FIG.7, REF.11
JOURNAL NUMBER: F0040AAH ISSN NO: 0387-0774
UNIVERSAL DECIMAL CLASSIFICATION: 621.385:621.397 621.382.002.2
LANGUAGE: Japanese COUNTRY OF PUBLICATION: Japan
DOCUMENT TYPE: Journal
ARTICLE TYPE: Commentary
MEDIA TYPE: Printed Publication

15/7/4 (Item 2 from file: 94)

DIALOG(R)File 94:JICST-EPlus

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02219733 JICST ACCESSION NUMBER: 94A0615185 FILE SEGMENT: JICST-E

Special issue : Production engineering of a liquid crystal display.

Contactless carrier device for a large and ultrathin type liquid
crystal glass substrate.

AKASHI HIROSHI (1)

(1) Sorarisachiken

Denshi Zairyo(Electronic Parts and Materials), 1994, VOL.33,NO.7,
PAGE.27-32, FIG.11, TBL.2

JOURNAL NUMBER: F0040AAH ISSN NO: 0387-0774

UNIVERSAL DECIMAL CLASSIFICATION: 621.385:621.397

LANGUAGE: Japanese COUNTRY OF PUBLICATION: Japan

DOCUMENT TYPE: Journal

ARTICLE TYPE: Commentary

MEDIA TYPE: Printed Publication

ABSTRACT: The "float chuck FU type" device which can meet the LCD
manufacturing process and carries a large and thin type glass substrate
which is contactless and non-dust is introduced. On this device, the
following are described : background of development, operation
principle, features, structure, examples of use, etc. This paper
describes the features of this equipment and the explanation of the
mechanism such as the airflow does not hit the glass substrate directly
when high speed airstream is spouted out the substrate.

15/7/5 (Item 3 from file: 94)

DIALOG(R)File 94:JICST-EPlus

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01940676 JICST ACCESSION NUMBER: 94A0128342 FILE SEGMENT: JICST-E

ID System. COB Assembly and The Reliability. A Method Which Establishes
Wire Bonding Condition of C-MOS Bare Chip IC.

IWAMAE YOSHIKI (1)

(1) Omuron

Omron Tech, 1993, VOL.33,NO.4, PAGE.286-290, FIG.8, TBL.5

JOURNAL NUMBER: S0266AAU ISSN NO: 0474-1315 CODEN: OMTKA

UNIVERSAL DECIMAL CLASSIFICATION: 681.327.2 621.382.002.2

LANGUAGE: Japanese COUNTRY OF PUBLICATION: Japan

DOCUMENT TYPE: Journal

ARTICLE TYPE: Commentary

MEDIA TYPE: Printed Publication

ABSTRACT: We have developed a small one, sized .PHI.8*5(mm), as the data
carrier of non - contact ID system. This data carrier is made of COB
assembly of bare chip IC in form of small one. In this company, COB
assembly (wire bonding assembly) on the glass-epoxy, print circuit
board is increasing and it is necessary for us to establish this
technology as soon as possible. C-MOS IC is different from Bi-Polar IC
and the silicone ingredient included in its pattern exerts a serious
influence on assembly stress. As a results, harder we set the wire
bonding force, bigger the damage to IC becomes. This time we have in
experiment and investigation of the COB assembly technology included ID
system's data carrier using Taguchi-Method from the following points of

views. (1) The influence of assembly stress by difference of the constitution between C-MOS IC and Bi-Polar IC. (2) How to set the most suitable wire bonding condition. (3) How to investigate the reliability. The result is that we have selectd control factors as the main factor in the assembly stress and have established how to set the most suitable condition and have developped applications to products.

(author abst.)

?show files;ds;bs98,9,16,160,148,621,636,441,20,813,15,88,442,444,457

File 155: MEDLINE(R) 1966-2002/May W1

File 144:Pascal 1973-2002/May W2

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File 5:Biosis Previews(R) 1969-2002/May W2

(c) 2002 BIOSIS

File 6:NTIS 1964-2002/May W3

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File 2:INSPEC 1969-2002/May W2

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File 434:SciSearch(R) Cited Ref Sci 1974-1989/Dec

(c) 1998 Inst for Sci Info

File 94:JICST-EPlus 1985-2002/Mar W4

(c) 2002 Japan Science and Tech Corp (JST)

File 35:Dissertation Abs Online 1861-2002/Apr

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Set	Items	Description
S1	72717	WIRELESS
S2	28920	NONCONTACT OR NON()CONTACT
S3	14174	CONTACTLESS
S4	805030	CARRIER? ?
S5	9982	TRANSPOUNDER? ?
S6	19678	TRANSMITTER? (2N) RECEIVER?
S7	87423	SILICONE
S8	52660	EPOXY()RESIN
S9	112	DUROPLASTIC OR DURAPLASTIC
S10	151436	CEMENT
S11	509020	CERAMIC? ?
S12	845	S1:S3(3N)S4:S6
S13	783550	S7:S11
S14	8	S12 AND S13
S15	5	RD (unique items)

15may02 14:39:12 User262807 Session D3145.2

\$1.45 0.454 DialUnits File155

\$1.45 Estimated cost File155

\$1.72 0.491 DialUnits File144
\$1.65 1 Type(s) in Format 7
\$0.21 1 Type(s) in Format 95 (KWIC)
\$1.86 2 Types
\$3.58 Estimated cost File144
\$1.15 0.205 DialUnits File5
\$1.15 Estimated cost File5
\$1.20 0.203 DialUnits File6
\$1.20 Estimated cost File6
\$2.92 0.450 DialUnits File2
\$2.92 Estimated cost File2
\$2.72 0.389 DialUnits File8
\$2.72 Estimated cost File8
\$0.35 0.146 DialUnits File99
\$0.21 1 Type(s) in Format 95 (KWIC)
\$0.21 1 Types
\$0.56 Estimated cost File99
\$0.22 0.101 DialUnits File238
\$0.22 Estimated cost File238
\$0.53 0.142 DialUnits File65
\$0.53 Estimated cost File65
\$0.31 0.107 DialUnits File77
\$0.31 Estimated cost File77
\$2.70 0.300 DialUnits File73
\$2.70 Estimated cost File73
\$6.14 0.359 DialUnits File34
\$6.14 Estimated cost File34
\$2.40 Estimated cost File434
\$1.15 0.330 DialUnits File94
\$4.05 3 Type(s) in Format 7
\$0.78 3 Type(s) in Format 95 (KWIC)
\$4.83 6 Types
\$5.98 Estimated cost File94
\$0.56 0.136 DialUnits File35
\$0.56 Estimated cost File35
OneSearch, 15 files, 3.953 DialUnits FileOS
\$1.08 TELNET
\$33.50 Estimated cost this search
\$33.55 Estimated total session cost 4.035 DialUnits

SYSTEM:OS - DIALOG OneSearch
File 98:General Sci Abs/Full-Text 1984-2002/Apr
(c) 2002 The HW Wilson Co.
File 9:Business & Industry(R) Jul/1994-2002/May 14
(c) 2002 Resp. DB Svcs.
File 16:Gale Group PROMT(R) 1990-2002/May 14
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File 621:Gale Group New Prod.Annou.(R) 1985-2002/May 14
(c) 2002 The Gale Group
File 636:Gale Group Newsletter DB(TM) 1987-2002/May 14
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File 441:ESPICOM Pharm&Med DEVICE NEWS 2002/May W2
 (c) 2002 ESPICOM Bus.Intell.
 File 20:Dialog Global Reporter 1997-2002/May 15
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 File 813:PR Newswire 1987-1999/Apr 30
 (c) 1999 PR Newswire Association Inc
 File 15:ABI/Inform(R) 1971-2002/May 15
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 *File 15: SELECT IMAGE AVAILABILITY FOR PROQUEST FILES
 ENTER 'HELP PROQUEST' FOR MORE
 File 88:Gale Group Business A.R.T.S. 1976-2002/May 14
 (c) 2002 The Gale Group
 File 442:AMA Journals 1982-2002/May B2
 (c) 2002 Amer Med Assn -FARS/DARS apply
 *File 442: PY,PD sort temporarily do not work.
 File 444:New England Journal of Med. 1985-2002/May W2
 (c) 2002 Mass. Med. Soc.
 File 457:The Lancet 1986-2000/Oct W1
 (c) 2000 The Lancet, Ltd.
 *File 457: Due to production changes at The Lancet, the updating of
 this file is delayed.

Set	Items	Description
---	-----	-----

?exs
 Executing TD214
 >>>SET HIGHLIGHT: use ON, OFF, or 1-5 characters
 S1 1406695 WIRELESS
 Processing
 Processed 10 of 15 files ...
 Completed processing all files

	4389	NONCONTACT
	3640369	NON
	8147744	CONTACT
	11097	NON (W) CONTACT
S2	15163	NONCONTACT OR NON()CONTACT
S3	6501	CONTACTLESS
S4	2284000	CARRIER? ?
S5	69956	TRANSPONDER? ?
	99741	TRANSMITTER?
	326942	RECEIVER?
S6	19927	TRANSMITTER? (2N) RECEIVER?
S7	41375	SILICONE
	46556	EPOXY
	189985	RESIN
S8	8598	EPOXY()RESIN
	32	DUROPLASTIC
	2	DURAPLASTIC
S9	34	DUROPLASTIC OR DURAPLASTIC
S10	189866	CEMENT
S11	179024	CERAMIC? ?

?ds

Set	Items	Description
S1	1406695	WIRELESS
S2	15163	NONCONTACT OR NON()CONTACT
S3	6501	CONTACTLESS

S4 2284000 CARRIER? ?
S5 69956 TRANSPONDER? ?
S6 19927 TRANSMITTER?(2N) RECEIVER?
S7 41375 SILICONE
S8 8598 EPOXY() RESIN
S9 34 DUROPLASTIC OR DURAPLASTIC
S10 189866 CEMENT
S11 179024 CERAMIC? ?
?s s1:s3(3n)s4:s6
Processed 10 of 15 files ...
Processing
Completed processing all files
1426253 S1:S3
2362944 S4:S6
S12 163318 S1:S3(3N)S4:S6
?s s7:s10
S13 238584 S7:S10
?s s12(s)s13
163318 S12
238584 S13
S14 14 S12(S)S13
?rd
>>>Duplicate detection is not supported for File 441.
>>>Records from unsupported files will be retained in the RD set.
...completed examining records
S15 5 RD (unique items)
?sort s15/all/pd,d
S16 5 Sort S15/ALL/PD,D
?t16/6,k,pd/all
>>>No matching display code(s) found in file(s): 442
16/6,K,PD/1 (Item 1 from file: 15)
DIALOG(R)File 15:(c) 2002 ProQuest Info&Learning. All rts. reserv.

02337942 111742866
The comeback kid
Mar 2002
LENGTH: 2 Pages
WORD COUNT: 1038

...ABSTRACT: Verizon. Then she flew to Europe to address perceptions of Lucent's global participation and cement its commitment to eight major customers. Her promise to wireless carrier customers: Lucent will talk less and do more. Russo is known for backing up her...

16/6,K,PD/2 (Item 2 from file: 16)
DIALOG(R)File 16:(c) 2002 The Gale Group. All rts. reserv.

09290417 Supplier Number: 80848048
I want my MP3: Could a wireless handset that includes an mp3 player be the latest winning device?
Dec 1, 2001
Word Count: 1211

... like that, the impact of 3G could be significant."

Webnoize agreed and predicts that if wireless carriers cement relationships with entertainment conglomerates, mobile access to music and video will boost annual revenues for...

16/6,K,PD/3 (Item 3 from file: 16)
DIALOG(R)File 16:(c) 2002 The Gale Group. All rts. reserv.

06672353 Supplier Number: 55814596
AT&T AND BT JOIN FORCES IN GLOBAL WIRELESS ALLIANCE.
Sept 20, 1999
Word Count: 711

(USE FORMAT 7 FOR FULLTEXT)
TEXT:

...are on GSM. Pact is designed to bolster AT&T and British Telecom position against wireless carriers such as Vodafone, which is working on potential U.S. joint venture with Bell Atlantic to cement its reach in eastern U.S.

16/6,K,PD/4 (Item 4 from file: 16)
DIALOG(R)File 16:(c) 2002 The Gale Group. All rts. reserv.

06393040 Supplier Number: 54812623
In Wireless World, MCI Reaches for a Pager; SkyTel merger leaves phone service lagging.(Company Business and Marketing)
June 7, 1999
Word Count: 309

(USE FORMAT 7 FOR FULLTEXT)
TEXT:
...MCI WorldCom Inc.'s planned \$1.8 billion merger with paging power SkyTel Corp. would cement its niche in the wireless world, the carrier still lacks what corporate users really want -- wireless phone service. And industry experts wonder if...

...of a wireless telephone network like AT&T's or Sprint's is hurting the carrier . "We think wireless is important, but we don't think [not having it] is limiting our growth," said...

16/6,K,PD/5 (Item 5 from file: 9)
DIALOG(R)File 9:(c) 2002 Resp. DB Svcs. All rts. reserv.

02235257
Chapter 7 Bell Tolls For Toll Free

August 31, 1998
WORD COUNT: 456

(USE FORMAT 7 OR 9 FOR FULLTEXT)

TEXT:
...Free are not.

What apparently sank Toll Free was its failure to cement partnerships with

wireless carders. Among the carriers it romanced were AT&T Wireless Services Inc., GTE Wireless and AirTouch Cellular. Lazar was...
?show files;ds;b350,344,347,371
File 98:General Sci Abs/Full-Text 1984-2002/Apr
(c) 2002 The HW Wilson Co.
File 9:Business & Industry(R) Jul/1994-2002/May 14
(c) 2002 Resp. DB Svcs.
File 16:Gale Group PROMT(R) 1990-2002/May 14
(c) 2002 The Gale Group
File 160:Gale Group PROMT(R) 1972-1989
(c) 1999 The Gale Group
File 148:Gale Group Trade & Industry DB 1976-2002/May 15
(c) 2002 The Gale Group
File 621:Gale Group New Prod.Annou.(R) 1985-2002/May 14
(c) 2002 The Gale Group
File 636:Gale Group Newsletter DB(TM) 1987-2002/May 14
(c) 2002 The Gale Group
File 441:ESPICOM Pharm&Med DEVICE NEWS 2002/May W2
(c) 2002 ESPICOM Bus.Intell.
File 20:Dialog Global Reporter 1997-2002/May 15
(c) 2002 The Dialog Corp.
File 813:PR Newswire 1987-1999/Apr 30
(c) 1999 PR Newswire Association Inc
File 15:ABI/Inform(R) 1971-2002/May 15
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File 88:Gale Group Business A.R.T.S. 1976-2002/May 14
(c) 2002 The Gale Group
File 442:AMA Journals 1982-2002/May B2
(c) 2002 Amer Med Assn -FARS/DARS apply
File 444:New England Journal of Med. 1985-2002/May W2
(c) 2002 Mass. Med. Soc.
File 457:The Lancet 1986-2000/Oct W1
(c) 2000 The Lancet, Ltd.

Set	Items	Description
S1	1406695	WIRELESS
S2	15163	NONCONTACT OR NON()CONTACT
S3	6501	CONTACTLESS
S4	2284000	CARRIER? ?
S5	69956	TRANSPONDER? ?
S6	19927	TRANSMITTER?(2N) RECEIVER?
S7	41375	SILICONE
S8	8598	EPOXY()RESIN
S9	34	DUROPLASTIC OR DURAPLASTIC
S10	189866	CEMENT
S11	179024	CERAMIC? ?
S12	163318	S1:S3(3N)S4:S6
S13	238584	S7:S10
S14	14	S12(S)S13
S15	5	RD (unique items)
S16	5	Sort S15/ALL/PD,D
		15may02 14:42:45 User262807 Session D3145.3
	\$0.20	0.082 DialUnits File98
\$0.20		Estimated cost File98
	\$0.90	0.168 DialUnits File9
	\$0.26	1 Type(s) in Format 95 (KWIC)
	\$0.26	1 Types

```

$1.16 Estimated cost File9
    $3.28    0.608 DialUnits File16
        $0.78  3 Type(s) in Format 95 (KWIC)
        $0.78  3 Types
$4.06 Estimated cost File16
    $0.53    0.098 DialUnits File160
$0.53 Estimated cost File160
    $4.51    0.835 DialUnits File148
$4.51 Estimated cost File148
    $1.66    0.308 DialUnits File621
$1.66 Estimated cost File621
    $2.10    0.389 DialUnits File636
$2.10 Estimated cost File636
    $0.64    0.088 DialUnits File441
$0.64 Estimated cost File441
    $0.77    0.771 DialUnits File20
$0.77 Estimated cost File20
    $0.26    0.264 DialUnits File813
$0.26 Estimated cost File813
    $1.26    0.232 DialUnits File15
        $0.26  1 Type(s) in Format 95 (KWIC)
        $0.26  1 Types
$1.52 Estimated cost File15
    $0.75    0.171 DialUnits File88
$0.75 Estimated cost File88
    $0.54    0.119 DialUnits File442
$0.54 Estimated cost File442
    $0.42    0.088 DialUnits File444
$0.42 Estimated cost File444
    $0.36    0.074 DialUnits File457
$0.36 Estimated cost File457
    OneSearch, 15 files, 4.295 DialUnits FileOS
$0.86 TELNET
$20.34 Estimated cost this search
$53.89 Estimated total session cost   8.329 DialUnits

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SYSTEM:OS - DIALOG OneSearch
File 350:Derwent WPIX 1963-2001/UD,UM &UP=200230
(c) 2002 Thomson Derwent
*File 350: Please see HELP NEWS 350 for details about U.S. provisional
applications. Also more updates in 2002.
File 344:CHINESE PATENTS ABS APR 1985-2002/APR
(c) 2002 EUROPEAN PATENT OFFICE
File 347:JAPIO Oct/1976-2001/Dec(Updated 020503)
(c) 2002 JPO & JAPIO
*File 347: JAPIO data problems with year 2000 records are now fixed.
Alerts have been run. See HELP NEWS 347 for details.
File 371:French Patents 1961-2002/BOPI 200209
(c) 2002 INPI. All rts. reserv.

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Set	Items	Description
-----	-------	-------------

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?exs

Executing TD214

>>>SET HIGHLIGHT: use ON, OFF, or 1-5 characters
S1 36524 WIRELESS

	5932	NONCONTACT
	1019443	NON
	1222127	CONTACT
	23116	NON (W) CONTACT
S2	28773	NONCONTACT OR NON () CONTACT
S3	12355	CONTACTLESS
S4	418743	CARRIER? ?
S5	5406	TRANSPOUNDER? ?
	142349	TRANSMITTER?
	294631	RECEIVER?
S6	33422	TRANSMITTER? (2N) RECEIVER?
S7	104039	SILICONE
	315650	EPOXY
	1076613	RESIN
S8	95942	EPOXY() RESIN
	408	DUROPLASTIC
	0	DURAPLASTIC
S9	408	DUROPLASTIC OR DURAPLASTIC
S10	93236	CEMENT
S11	366699	CERAMIC? ?

?ds

Set	Items	Description
S1	36524	WIRELESS
S2	28773	NONCONTACT OR NON () CONTACT
S3	12355	CONTACTLESS
S4	418743	CARRIER? ?
S5	5406	TRANSPOUNDER? ?
S6	33422	TRANSMITTER? (2N) RECEIVER?
S7	104039	SILICONE
S8	95942	EPOXY() RESIN
S9	408	DUROPLASTIC OR DURAPLASTIC
S10	93236	CEMENT
S11	366699	CERAMIC? ?

?s s1:s3(3n)s4:s6

77133	S1:S3
454861	S4:S6

S12 1255 S1:S3(3N)S4:S6

?s s7:s10

S13 285675 S7:S10

?s s12 and s13

1255	S12
285675	S13

S14 17 S12 AND S13

?idpat

New file order will be: 344,350

Duplicates will be matched against primary file: 344

Press ENTER to accept or enter preferred primary file number.

?350

New file order: 350, 344, 347, 371

...completed examining records

S15 17 IDPAT (sorted in duplicate/non-duplicate order)

Summary:

S15 has 17 records ordered as follows:

1 patent groups (records 1-2)

15 patent records without duplicates (records 3-17)

Group Table:

Groups	Total in Group	Primary Records	Record Numbers	Duplicates	Record Numbers
G1	2	F350	1	F347	2

1. Show Group Table
2. Show Summary
3. Quit
4. TYPE or PRINT Selected Records
5. TYPE or PRINT Primary and Non-Duplicate Records

Enter an option (e.g., 4).

?5

S16 16 IDPAT (primary/non-duplicate records only)
Press ENTER to TYPE records or enter PR to PRINT records via e-mail, fax,
or postal delivery.

?

Enter format number or two-character display tag(s) (e.g., TI, PA) or
enter Q to return to command mode.

?ti;all;3

Enter record(s) to be TYPEd (e.g., ALL or a range to receive a desired
number of Primary/Non-duplicate records, e.g., 1-10), or enter Q to return
to command mode.

16/TI/1 (Item 1 from file: 350)
DIALOG(R) File 350:(c) 2002 Thomson Derwent. All rts. reserv.

Non - contact data carrier e.g. tag for communicating information of
external device, has resin sealed antenna coil arranged surrounding
silicone resin sealed circuit board

16/TI/2 (Item 2 from file: 350)
DIALOG(R) File 350:(c) 2002 Thomson Derwent. All rts. reserv.

Rotor temperature abnormality detector for pulverisation mill - has
temperature detector fixed to rotating bearing to detect temperature and
activate lubrication system

16/TI/3 (Item 3 from file: 350)
DIALOG(R) File 350:(c) 2002 Thomson Derwent. All rts. reserv.

Non - contact data carrier package - has buffer layer comprising
gel-like resin made from silicone resin film, covering area including
junction of circuit board and antenna coil

16/TI/4 (Item 4 from file: 350)
DIALOG(R) File 350:(c) 2002 Thomson Derwent. All rts. reserv.

Image formation method by electrophotography - by reversal development
using silicone resin-coated magnetic carrier

16/TI/5 (Item 5 from file: 350)

DIALOG(R)File 350:(c) 2002 Thomson Derwent. All rts. reserv.

Developing electrostatic latent image having high density - using developer including carrier obtd. by coating particles with resin layer including silicone resin and toner

16/TI/6 (Item 6 from file: 347)

DIALOG(R)File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

DATA CARRIER MODULE, DATA CARRIER, AND METHOD FOR MANUFACTURING DATA CARRIER

16/TI/7 (Item 7 from file: 347)

DIALOG(R)File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

COMPONENT FOR NONCONTACT DATA CARRIER , NONCONTACT DATA CARRIER AND MANUFACTURING METHOD FOR NONCONTACT DATA CARRIER

16/TI/8 (Item 8 from file: 347)

DIALOG(R)File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

PRESSURE SENSOR MODULE AND METHOD FOR MANUFACTURE IT

16/TI/9 (Item 9 from file: 347)

DIALOG(R)File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

ANTENNA MAGNETIC CORE FOR NONCONTACT DATA CARRIER , PRODUCTION OF THE CORE, ANTENNA FOR NONCONTACT DATA CARRIER USING THE CORE AND NONCONTACT DATA CARRIER

16/TI/10 (Item 10 from file: 347)

DIALOG(R)File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

NONCONTACT DATA CARRIER

16/TI/11 (Item 11 from file: 347)

DIALOG(R)File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

NON - CONTACT DATA CARRIER AND MANUFACTURE OF NON - CONTACT DATA CARRIER

16/TI/12 (Item 12 from file: 347)

DIALOG(R)File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

LABEL TYPE NONCONTACT DATA CARRIER

16/TI/13 (Item 13 from file: 347)

DIALOG(R)File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

LABEL TYPE NONCONTACT DATA CARRIER

16/TI/14 (Item 14 from file: 347)
DIALOG(R) File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

ANTENNA MAGNETIC CORE FOR NONCONTACT DATA CARRIER , ANTENNA FOR
NONCONTACT DATA CARRIER , AND NONCONTACT DATA CARRIER

16/TI/15 (Item 15 from file: 347)
DIALOG(R) File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

TABLEWARE WITH NON - CONTACT CARRIER AND MANUFACTURE THEREOF

16/TI/16 (Item 16 from file: 347)
DIALOG(R) File 347:(c) 2002 JPO & JAPIO. All rts. reserv.

MANUFACTURE OF NON - CONTACT DATA CARRIER

Summary:

S15 has 17 records ordered as follows:

 1 patent groups (records 1-2)
 15 patent records without duplicates (records 3-17)

1. Show Group Table 4. TYPE or PRINT Selected Records
2. Show Summary 5. TYPE or PRINT Primary and Non-Duplicate Records
3. Quit

Enter an option (e.g., 4).

Exiting IDPAT. Original file order reinstated, enter SHOW FILES to review
file order. Enter DISPLAY SETS (DS) to review existing sets.
?t16/7/1,3-8,10-13,16

16/7/1 (Item 1 from file: 350)
DIALOG(R) File 350:Derwent WPIX
(c) 2002 Thomson Derwent. All rts. reserv.

013253685 **Image available**
WPI Acc No: 2000-425568/200037

Non - contact data carrier e.g. tag for communicating information of
external device, has resin sealed antenna coil arranged surrounding
silicone resin sealed circuit board

Patent Assignee: TOSHIBA KK (TOKE)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 2000113154	A	20000421	JP 98279137	A	19980930	200037 B

Priority Applications (No Type Date): JP 98279137 A 19980930

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 2000113154	A	5	G06K-019/077	

Abstract (Basic): JP 2000113154 A

NOVELTY - A copper antenna coil (4) is arranged surrounding the

circuit board (3) in which IC chips are mounted. ABS resin (5) is provided to the seal. The antenna coil and silicone resin (6) which is softer than ABS resin seals the circuit board. The ABS resin seal surrounds the silicone resin seal.

DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for manufacturing method of data carrier.

USE - For e.g. non-contact tag affixed to goods for communicating information of external device.

ADVANTAGE - Destruction of internal components like IC chip is reduced as attenuation of oscillation is carried out by silicone resin before the impact travels to IC chip.

DESCRIPTION OF DRAWING(S) - The figure shows sectional side view of data carrier.

Circuit board (3)
Copper antenna coil (4)
ABS resin (5)
Silicone resin (6)
pp; 5 DwgNo 3/11

Derwent Class: A85; L03; P76; T04; V04; W02

International Patent Class (Main): G06K-019/077

International Patent Class (Additional): B42D-015/10; G06K-019/07

16/7/3 (Item 3 from file: 350)

DIALOG(R) File 350:Derwent WPIX

(c) 2002 Thomson Derwent. All rts. reserv.

012492226 **Image available**

WPI Acc No: 1999-298334/199925

Non - contact data carrier package - has buffer layer comprising gel-like resin made from silicone resin film, covering area including junction of circuit board and antenna coil

Patent Assignee: TOSHIBA CHEM CORP (TOSM)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 11102424	A	19990413	JP 97262320	A	19970926	199925 B

Priority Applications (No Type Date): JP 97262320 A 19970926

Patent Details:

Patent No Kind Lan Pg Main IPC Filing Notes

JP 11102424 A 6 G06K-019/07

Abstract (Basic): JP 11102424 A

NOVELTY - The area including circuit board (2) its junction and an antenna coil (1) is covered by a buffer layer (3') comprising gel-like resin (3b) made from a silicone resin film (3a). An outer cladding surrounds the circuit board, the buffer layer and the antenna coil.

USE - For loading various rubber goods.

ADVANTAGE - Prevents destruction of internal component caused due to stress generated by external mechanical shock. Since a buffer layer comprising gel-like resin is used, handling is simplified and workability is improved.

DESCRIPTION OF DRAWING(S) - The figure shows the sectional view of non contact data carrier package. (1) Antenna coil; (2) Circuit board(3') Buffer layer; (3a) Silicone resin film; (3b) Gel-like resin.

Dwg.4/6

Derwent Class: A85; L03

International Patent Class (Main): G06K-019/07

International Patent Class (Additional): G06K-019/00

16/7/4 (Item 4 from file: 350)

DIALOG(R) File 350:Derwent WPIX

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011398896 **Image available**

WPI Acc No: 1997-376803/199735

Image formation method by electrophotography - by reversal development
using silicone resin-coated magnetic carrier

Patent Assignee: KONICA CORP (KONS)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 9160306	A	19970620	JP 95321686	A	19951211	199735 B

Priority Applications (No Type Date): JP 95321686 A 19951211

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 9160306	A	7		

Abstract (Basic): JP 9160306 A

The image formation method forms a superimposed colour image by repeating a series of the processes, reversal-developing the latent image on the photosensitive material, formed by the charging and image-exposing. The reversal development uses two components (the carrier and the toner) type non - contact type development. The carrier is silicone resin-coated magnetic carrier.

The surface magnetic field on the development sleeve in the development region of the developing apparatus is 1000 G - 2500 G. The volume-average particle diameter, the saturated magnetisation, and the specific electrical resistance of the silicone resin-coated magnetic carrier are 10 - 50 microns, 10 - 50 e mu /g, and 100000 Omega cm. - 1 x 1012 Omega cm. respectively

ADVANTAGE - The colour image formation method gives image with excellent high image quality. The apparatus has excellent high durability.

Dwg.1/2

Derwent Class: A26; A89; G08; P84; S06

International Patent Class (Main): G03G-009/113

International Patent Class (Additional): G03G-015/01; G03G-015/08

16/7/5 (Item 5 from file: 350)

DIALOG(R) File 350:Derwent WPIX

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009411683 **Image available**

WPI Acc No: 1993-105194/199313

Developing electrostatic latent image having high density - using developer including carrier obtd. by coating particles with resin layer including silicone resin and toner

Patent Assignee: KONICA CORP (KONS)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 5045936	A	19930226	JP 91202893	A	19910813	199313 B

Priority Applications (No Type Date): JP 91202893 A 19910813

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 5045936	A	7	G03G-009/113	

Abstract (Basic): JP 5045936 A

Developer includes carrier and toner. The developer is supplied to a developing area in an AC electric field while controlling the developer amt. by pressing a developer amt. controlling member onto the developer layer of a developer transporting member, for developing a latent image on an image holding member by non - contact development. The carrier is obtd. by coating particles with a resin coating layer including silicone resin by mechanical impact force, and the carrier has less than 60 microns of wt. average particle size.

The coating resin of the carrier pref. comprises silicone resin fine particles and styrene and/or acryl resin fine particles, or copolymer resin fine particles of them.

USE/ADVANTAGE - Toner spent to the carrier may be prevented, and scattering of the toner is prevented. An image of high density and high quality may be obtd..

Dwg.1/3

Derwent Class: A89; G08; P84; S06

International Patent Class (Main): G03G-009/113

16/7/6 (Item 6 from file: 347)

DIALOG(R) File 347:JAPIO

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07015807 **Image available**

DATA CARRIER MODULE, DATA CARRIER, AND METHOD FOR MANUFACTURING DATA CARRIER

PUB. NO.: 2001-243437 [JP 2001243437 A]

PUBLISHED: September 07, 2001 (20010907)

INVENTOR(s): KOBAYASHI MIDORI

APPLICANT(s): TOSHIBA CHEM CORP

APPL. NO.: 2000-054504 [JP 200054504]

FILED: February 29, 2000 (20000229)

ABSTRACT

PROBLEM TO BE SOLVED: To provide a non - contact data carrier which can be made improved in mechanical strength, small in size and light in weight, and manufactured by simple technology.

SOLUTION: An IC chip 62, a capacitor 64, and a resistance 65 are mounted on a lead frame 61 and an area except a sensor mount part 65a is molded by transfer by using epoxy resin 66. The IC chip 62, capacitor 64, and resistance 65 are sealed and a recessed cavity part 65b as the mount space for a pressure sensor element 7 is formed. Then the pressure sensor element 7 is mounted on the sensor mount part 65a and the gap between the pressure sensor element 7 and recessed cavity 65b is filled with silicone resin

70, which is set. Then an antenna coil is connected to the data carrier module 6 obtained by cutting tie bars of the data carrier module 6 to manufacture the contactless data carrier 3.

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16/7/7 (Item 7 from file: 347)
DIALOG(R) File 347:JAPIO
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07000432 **Image available**
COMPONENT FOR NONCONTACT DATA CARRIER , NONCONTACT DATA CARRIER AND MANUFACTURING METHOD FOR NONCONTACT DATA CARRIER

PUB. NO.: 2001-228042 [JP 2001228042 A]
PUBLISHED: August 24, 2001 (20010824)
INVENTOR(s): KOBAYASHI MIDORI
HANAMURA KENICHIRO
MIYAUCHI TAKANORI
APPLICANT(s): TOSHIBA CHEM CORP
APPL. NO.: 2000-040113 [JP 200040113]
FILED: February 17, 2000 (20000217)

ABSTRACT

PROBLEM TO BE SOLVED: To provide a manufacturing method for a noncontact data carrier , whose precise pressure responsiveness can be displayed and whose mechanical strength can be increased.

SOLUTION: A printed circuit board 22, on which an IC chip 21 and a pressure sensor element 18 are mounted, is mounted inside an armor container 24. Internal calibration terminals 23 and antenna internal connecting terminals 151, which are installed on the printed-circuit board 22 and external calibration terminals 25 and antenna connecting terminals 152 which are installed, so as to be passed through to the outside from the inside of the armor container 24 are subjected to wire-bonding respectively. A lid 29, which has an opening part 28 is put on the armor container 24, a silicone resin 27 is filled into the armor container 24, and the component 30 for the data carrier is manufactured. After the component 30 for the data carrier is calibrated, antennas 15 are connected to the antenna connecting terminals 152 at the outside of the armor container 24, to manufacture noncontact data carrier 3.

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16/7/8 (Item 8 from file: 347)
DIALOG(R) File 347:JAPIO
(c) 2002 JPO & JAPIO. All rts. reserv.

06743779 **Image available**
PRESSURE SENSOR MODULE AND METHOD FOR MANUFACTURE IT

PUB. NO.: 2000-329632 [JP 2000329632 A]
PUBLISHED: November 30, 2000 (20001130)
INVENTOR(s): KOBAYASHI MIDORI
FURUHASHI JUN

APPLICANT(s): TOSHIBA CHEM CORP
APPL. NO.: 11-136109 [JP 99136109]
FILED: May 17, 1999 (19990517)

ABSTRACT

PROBLEM TO BE SOLVED: To obtain a compact pressure sensor module that can be manufactured easily and inexpensively and has large bending strength.

SOLUTION: A lead frame 4 where a circuit part for composing a pressure sensor and an IC chip 3 (chip parts 8) for composing the circuit part of a non - contact data carrier are mounted is subjected to transfer forming by an epoxy resin or the like, thus manufacturing a resin forming body. At this time, a cavity 6 where a lead frame surface for mounting a pressure sensor chip 2 is exposed to a bottom surface is formed at a resin forming body 5. The pressure sensor chip 2 is mounted into the cavity 6, a pressure transferring resin 7 such as a silicone resin is filled into the cavity 6, and the pressure sensor chip 2 is sealed by the resin. Then, an unneeded lead frame part is cut for calibrating the pressure sensor, thus obtaining a pressure sensor module 1.

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16/7/10 (Item 10 from file: 347)
DIALOG(R) File 347:JAPIO
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06736694 **Image available**
NONCONTACT DATA CARRIER

PUB. NO.: 2000-322541 [JP 2000322541 A]
PUBLISHED: November 24, 2000 (20001124)
INVENTOR(s): FURUHASHI JUN
TANAKA NOBUO
APPLICANT(s): TOSHIBA CHEM CORP
APPL. NO.: 11-131911 [JP 99131911]
FILED: May 12, 1999 (19990512)

ABSTRACT

PROBLEM TO BE SOLVED: To provide a noncontact data carrier of high sensitivity by reducing the force that is applied to the magnetic core of an antenna due to the stress caused by the heat contraction or the hardening contraction of resin when an internal parts is sealed by the resin.

SOLUTION: An almost cylindrical antenna magnetic core is obtained by winding an amorphous magnetic alloy thin belt of an Fe group, a Co group or an Ni group, etc., in one or more layers according to the shape of a sheath case 30 of a noncontact data carrier 1. Then the antenna magnetic core is put into a cylindrical bobbin 22 which is made of the polyamide resin, etc., and contains a coil 23 where a copper wire is wound round. Thus, a transmitting and receiving antenna 20 is obtained. Then the antenna 20 and a circuit parts 10 are put into the case 30 and the elastic and fluid hardening resin such as the urethane resin, silicone resin and epoxy resin is injected into the case 30 and solidified. Then the parts 10 is sealed up by the sealing resin 40 serving as an elastic body. Thus, the carrier 1 is obtained.

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16/7/11 (Item 11 from file: 347)
DIALOG(R) File 347:JAPIO
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06656922 **Image available**
NON - CONTACT DATA CARRIER AND MANUFACTURE OF NON - CONTACT DATA
CARRIER

PUB. NO.: 2000-242745 [JP 2000242745 A]
PUBLISHED: September 08, 2000 (20000908)
INVENTOR(s): KOBAYASHI MIDORI
APPLICANT(s): TOSHIBA CHEM CORP
APPL. NO.: 11-041586 [JP 9941586]
FILED: February 19, 1999 (19990219)

ABSTRACT

PROBLEM TO BE SOLVED: To protect and strengthen the rear surface of an IC chip at a low cost and to reduce a fault occurrences in the IC chip in a non - contact data carrier on which the thin IC chip is mounted by a flip chip method.

SOLUTION: A sealing resin film (21) is formed on the rear surface and side faces of a silicone wafer (20) on which a circuit pattern is formed with thermosetting resin such as epoxy resin , or a resin sheet such as polyethersulfane and a metal sheet (23) such as aluminum are adhered with an adhesive 24 such as the epoxy resin . Next, an IC chip 10 where a rear surface protective layer 12 is formed on the rear surface is obtained by dicing the wafer (20). Subsequently, the chip 10 is mounted on a thin film-shaped antenna coil 1 formed on a resin sheet 2 by a flip chip method. A non - contact data carrier is obtained by adhering another resin sheet 2 on the sheet 2 and sealing with the sheets 2 and an adhesive layer 4.

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16/7/12 (Item 12 from file: 347)
DIALOG(R) File 347:JAPIO
(c) 2002 JPO & JAPIO. All rts. reserv.

06520088 **Image available**
LABEL TYPE NONCONTACT DATA CARRIER

PUB. NO.: 2000-105807 [JP 2000105807 A]
PUBLISHED: April 11, 2000 (20000411)
INVENTOR(s): FURUHASHI JUN
APPLICANT(s): TOSHIBA CHEM CORP
APPL. NO.: 10-275413 [JP 98275413]
FILED: September 29, 1998 (19980929)

ABSTRACT

PROBLEM TO BE SOLVED: To provide a disposable noncontact data carrier which is hardly reusable when detached from an article after being attached

and suitable for the purpose of protection against an illegal act.

SOLUTION: An antenna 2, made of a conductive paste layer, for sending and receiving signals to and from external device without contacting is formed by applying and then hardening conductive paste on a base material in to a specific pattern. On the antenna 2, an IC chip 1 provided with bumps 1a is mounted with an anisotropic conductive adhesive, etc. Then an adhesive layer 4 which covers the IC chip 1 and antenna 2 is formed of an acryl-based adhesive, etc., on the base material 3 and a peeling liner 5 is laminated on the adhesive layer 4 and united in a sheet shape to manufacture the label type noncontact data carrier 20. Before the conductive paste layer is formed, a peeling agent such as silicone resin is applied in a specific area 6 on the base material 3 and an easy-to-break process is performed so that the metal thin film is easily broken.

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16/7/13 (Item 13 from file: 347)
DIALOG(R)File 347:JAPIO
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06520087 **Image available**
LABEL TYPE NONCONTACT DATA CARRIER

PUB. NO.: 2000-105806 [JP 2000105806 A]
PUBLISHED: April 11, 2000 (20000411)
INVENTOR(s): FURUHASHI JUN
APPLICANT(s): TOSHIBA CHEM CORP
APPL. NO.: 10-275412 [JP 98275412]
FILED: September 29, 1998 (19980929)

ABSTRACT

PROBLEM TO BE SOLVED: To provide disposable noncontact data carrier which is hardly reusable when detached from an article after being attached and suitable for the purpose of protection against an illegal act.

SOLUTION: A metal thin film formed on a base material by vapor deposition, etc., is etched into a specific pattern to form an antenna 2 for sending and receiving signals to and from external equipment without contacting. An IC chip 1 provided with bumps 1a is mounted on the antenna 2 with an anisotropic conductive adhesive, etc. Then an adhesive layer 4 which covers the IC chip 1 and antenna 2 is formed of an acryl-based adhesive, etc., on the base material 3 and a peeling liner 5 is laminated on the adhesive layer 4 and united in a sheet shape to manufacture a label type noncontact data carrier 20. Before the metal thin film is formed, a peeling agent such as silicone resin is applied in a specific area 6 on the base material 3 and an easy-to-break process is performed so that the metal thin film is easily broken.

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16/7/16 (Item 16 from file: 347)
DIALOG(R)File 347:JAPIO
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06008290 **Image available**

MANUFACTURE OF NON - CONTACT DATA CARRIER

PUB. NO.: 10-291390 [JP 10291390 A]
PUBLISHED: November 04, 1998 (19981104)
INVENTOR(s): FURUHATA KENICHI
 FURUHASHI JUN
 IRIE YOSHIKAZU
APPLICANT(s): TOSHIBA CHEM CORP [460552] (A Japanese Company or Corporation), JP (Japan)
APPL. NO.: 09-101884 [JP 97101884]
FILED: April 18, 1997 (19970418)

ABSTRACT

PROBLEM TO BE SOLVED: To improve a manufacturing yield by facilitating a thickness reduction of resin-sealed non - contact data carrier and the manufacture.

SOLUTION: This manufacturing method comprises the steps of hot press molding to obtain sheathing resin 7 of non - contact data carrier in a reduced pressure atmosphere, and introducing fluid 10 such as gas or liquid into a sealed space 11 of the press as pressurizing means to raise pressure in the space 11. In this case, as the pressure, a structure for applying to a material to be molded via a pressurizing plate 12 made of an elastic material such as silicone rubber is used. Such pressurizing means is used to avoid concentration of excess pressure to an internal component 4 at the time of molding by a hot pressing method, the possibility of damaging the component 4 can be remarkably reduced, thereby improving its manufacturing yield.

?show files;ds;b348,349

File 350:Derwent WPIX 1963-2001/UD,UM &UP=200230

 (c) 2002 Thomson Derwent

File 344:CHINESE PATENTS ABS APR 1985-2002/APR

 (c) 2002 EUROPEAN PATENT OFFICE

File 347:JAPIO Oct/1976-2001/Dec(Updated 020503)

 (c) 2002 JPO & JAPIO

File 371:French Patents 1961-2002/BOPI 200209

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Set	Items	Description
S1	36524	WIRELESS
S2	28773	NONCONTACT OR NON()CONTACT
S3	12355	CONTACTLESS
S4	418743	CARRIER? ?
S5	5406	TRANSPOUNDER? ?
S6	33422	TRANSMITTER?(2N) RECEIVER?
S7	104039	SILICONE
S8	95942	EPOXY()RESIN
S9	408	DUROPLASTIC OR DURAPLASTIC
S10	93236	CEMENT
S11	366699	CERAMIC? ?
S12	1255	S1:S3(3N)S4:S6
S13	285675	S7:S10
S14	17	S12 AND S13
S15	17	IDPAT (sorted in duplicate/non-duplicate order)
S16	16	IDPAT (primary/non-duplicate records only)

15may02 14:46:37 User262807 Session D3145.4

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      $5.96  9 Types
$20.78  Estimated cost File350
      $1.03  0.098 DialUnits File344
$1.03  Estimated cost File344
      $6.71  0.613 DialUnits File347
      $12.80 8 Type(s) in Format  7
      $0.00 11 Type(s) in Format  6 (UDF)
      $12.80 19 Types
$19.51  Estimated cost File347
      $0.43  0.095 DialUnits File371
$0.43  Estimated cost File371
OneSearch, 4 files, 2.034 DialUnits FileOS
$0.86  TELNET
$42.61  Estimated cost this search
$96.50  Estimated total session cost 10.364 DialUnits

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SYSTEM:OS - DIALOG OneSearch
File 348:EUROPEAN PATENTS 1978-2002/May W01
(c) 2002 European Patent Office
File 349:PCT FULLTEXT 1983-2002/UB=20020509,UT=20020502
(c) 2002 WIPO/Univentio

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	657818	NON
	456748	CONTACT
	7237	NON (W) CONTACT
S2	8024	NONCONTACT OR NON() CONTACT
S3	3138	CONTACTLESS
S4	219983	CARRIER? ?
S5	5461	TRANSPONDER? ?
	58157	TRANSMITTER?
	92073	RECEIVER?
S6	24274	TRANSMITTER? (2N) RECEIVER?
S7	67189	SILICONE
	64852	EPOXY
	158043	RESIN
S8	21221	EPOXY() RESIN
	178	DUROPLASTIC
	3	DURAPLASTIC
S9	180	DUROPLASTIC OR DURAPLASTIC
S10	18994	CEMENT
S11	77745	CERAMIC? ?
?s s1:s3(3n)s4:s6		
	43921	S1:S3
	239298	S4:S6
S12	1433	S1:S3(3N)S4:S6
?s s7:s11		

S13 161161 S7:S11
?s s12(s)s13
 1433 S12
 161161 S13
S14 3 S12(S)S13
?t14/6/all

14/6/1 (Item 1 from file: 348)
01274160
ADHESION LABEL
KLEBEETIKETT
ETIQUETTE D'ADHESION
LANGUAGE (Publication,Procedural,Application): English; English; Japanese
FULLTEXT AVAILABILITY:
Available Text Language Update Word Count
 CLAIMS A (English) 200146 234
 SPEC A (English) 200146 3483
Total word count - document A 3717
Total word count - document B 0
Total word count - documents A + B 3717

14/6/2 (Item 2 from file: 348)
00277394
Device for transmitting electric energy to computers and data nets.
Anordnung zum Überbringen von elektrischer Energie zu Computern und
Datennetzwerken.
Dispositif pour transferer de l'energie electrique aux ordinateurs et
reseaux de donnees.
LANGUAGE (Publication,Procedural,Application): English; English; English
FULLTEXT AVAILABILITY:
Available Text Language Update Word Count
 CLAIMS B (English) EPBBF1 952
 CLAIMS B (German) EPBBF1 950
 CLAIMS B (French) EPBBF1 992
 SPEC B (English) EPBBF1 4405
Total word count - document A 0
Total word count - document B 7299
Total word count - documents A + B 7299

14/6/3 (Item 3 from file: 348)
00257549
Developing method for electrostatic latent image
Entwicklungsverfahren fur latente elektrostatische Bilder
Procede pour developper des images latentes electrostatiques
LANGUAGE (Publication,Procedural,Application): English; English; English
FULLTEXT AVAILABILITY:
Available Text Language Update Word Count
 CLAIMS B (English) 9710W2 479
 CLAIMS B (German) 9710W2 453
 CLAIMS B (French) 9710W2 529
 SPEC B (English) 9710W2 15690
Total word count - document A 0
Total word count - document B 17151
Total word count - documents A + B 17151
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14/3,AB/2 (Item 2 from file: 348)
DIALOG(R) File 348:EUROPEAN PATENTS
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00277394

Device for transmitting electric energy to computers and data nets.
Anordnung zum Überbringen von elektrischer Energie zu Computern und
Datennetzwerken.
Dispositif pour transferer de l'energie electrique aux ordinateurs et
reseaux de donnees.

PATENT ASSIGNEE:

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(applicant designated states: BE;DE;FR;GB;IT;NL;SE)

INVENTOR:

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LEGAL REPRESENTATIVE:

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PATENT (CC, No, Kind, Date): EP 260238 A2 880316 (Basic)
EP 260238 A3 900221
EP 260238 B1 940119

APPLICATION (CC, No, Date): EP 87850260 870828;

PRIORITY (CC, No, Date): SE 863805 860911

DESIGNATED STATES: BE; DE; FR; GB; IT; NL; SE

INTERNATIONAL PATENT CLASS: H01L-041/08;

ABSTRACT EP 260238 A2

A device for transmitting electric energy to electric equipment, primarily computers and data nets, which device is intended to be connected between a voltage source and the electric equipment. The invention is characterized in that it is provided with a generator (30,31) comprising a piezo-electric element, which generator is intended to be connected to said voltage source and to generate a high-frequency mechanical wave motion, that a bar-shaped transmission member (32) is provided to transmit said motion to a receiver (33-35), which transmission member comprises a non-magnetic and electrically insulating material, in which the mechanical wave motion can be conducted, that said receiver, which is intended to be connected to the electric equipment, is capable to convert said mechanical wave motion into an electrically varying voltage by means of a piezo-electric element (33), which is in a mechanical connection with said transmission member.

ABSTRACT WORD COUNT: 147

LANGUAGE (Publication,Procedural,Application): English; English; English
FULLTEXT AVAILABILITY:

Available	Text	Language	Update	Word Count
	CLAIMS B	(English)	EPBBF1	952
	CLAIMS B	(German)	EPBBF1	950
	CLAIMS B	(French)	EPBBF1	992
	SPEC B	(English)	EPBBF1	4405
Total word count - document A				0
Total word count - document B				7299
Total word count - documents A + B				7299
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File 348:EUROPEAN PATENTS 1978-2002/May W01

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ds;show files

Set	Items	Description
S1	5	((WIRELESS OR NONCONTACT OR NON()CONTACT) ()CARRIER OR TRANSPONDER) AND (EMBED? OR ENCAS?) AND (SILICON? OR EPOXY OR RESIN OR CEMENT OR CERAMIC?)
S2	1079520	((WIRELESS OR NONCONTACT OR NON()CONTACT) ()CARRIER? OR TRANSPONDER? OR SENSOR?)
S3	5127026	MEDICAL()DEVICE? OR SURGER? OR SURGICA? OR CHIRUG? OR ENDOSCOP?
S4	299534	EMBED? OR ENCAS?
S5	1846562	SILICON? OR EPOXY? OR RESIN? ? OR CEMENT? OR CERAMIC?
S6	17	S2 AND S3 AND S4 AND S5
S7	16	RD (unique items)
File	5:Biosis Previews(R) 1969-2002/May W2	
		(c) 2002 BIOSIS
File	155:MEDLINE(R) 1966-2002/May W2	
File	34:SciSearch(R) Cited Ref Sci 1990-2002/May W3	
		(c) 2002 Inst for Sci Info
File	434:SciSearch(R) Cited Ref Sci 1974-1989/Dec	
		(c) 1998 Inst for Sci Info
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		(c) 2002 Elsevier Science B.V.
File	2:INSPEC 1969-2002/May W2	
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File	6:NTIS 1964-2002/Jun W1	
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File	77:Conference Papers Index 1973-2002/Mar	
		(c) 2002 Cambridge Sci Abs
File	99:Wilson Appl. Sci & Tech Abs 1983-2002/Apr	
		(c) 2002 The HW Wilson Co.
File	94:JICST-EPlus 1985-2002/Mar W4	
		(c) 2002 Japan Science and Tech Corp(JST)
File	35:Dissertation Abs Online 1861-2002/Apr	
		(c) 2002 ProQuest Info&Learning
File	238:Abs. in New Tech & Eng. 1981-2002/May	
		(c) 2002 Reed-Elsevier (UK) Ltd.
File	65:Inside Conferences 1993-2002/May W2	
		(c) 2002 BLDSC all rts. reserv.
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Set	Items	Description
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S3	1164	CHIRUG?
S4	1521754	S2 OR S3
S5	0	S1 AND S4
S6	0	RD (unique items)
S7	592581	SHOCK?
S8	0	S1 AND S7
S9	0	RD (unique items)
S10	77523	(ENVIRONMENTAL? OR THERMAL? OR MECHANICAL? OR ELECTRICAL? - OR LOAD?) (3N)S7
S11	0	S1 AND S10
S12	0	RD (unique items)
S13	8	S1
S14	5	RD (unique items)
File	2:INSPEC 1969-2002/May W2	
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File	6:NTIS 1964-2002/Jun W1	
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		(c) 2002 Paint Research Assn.
File	32:METADEX(R) 1966-2002/Jul B1	
		(c) 2002 Cambridge Scientific Abs
File	33:Aluminium Ind Abs 1968-2002/Jun	
		(c) 2002 Cambridge Scientific Abs
File	34:SciSearch(R) Cited Ref Sci 1990-2002/May W3	
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File	96:FLUIDEX 1972-2002/May	
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		(c) 2002 The HW Wilson Co.
File	103:Energy SciTec 1974-2002/Apr B2	
		(c) 2002 Contains copyrighted material
File	105:AESIS 1851-2001/Jul	
		(c) 2001 Australian Mineral Foundation Inc
File	108:AEROSPACE DATABASE 1962-2002/APR	
		(c) 2002 AIAA
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		(c) 2002 Fraunhofer-IRB
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File 370:Science 1996-1999/Jul W3
(c) 1999 AAAS

File 399:CA SEARCH(R) 1967-2002/UD=13620
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(c) 1998 Inst for Sci Info